

Chapter 19: Thermal Properties

ISSUES TO ADDRESS...

- How do _____ to the application of heat?
- How do we define and measure...
 - _____?
 - thermal expansion?
 - _____?
 - thermal shock resistance?
- How do the _____ of ceramics, metals, and polymers differ?

Chapter 19 - 1

Heat Capacity

The ability of a material to absorb _____

- Quantitatively: The _____ required to produce a unit rise in _____ for one mole of a material.

heat capacity (J/mol-K) $C = \frac{dQ}{dT}$
energy input (J/mol)
temperature change (K)

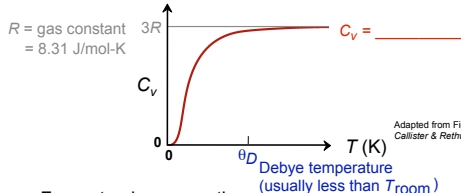
- Two ways to measure heat _____:
 - C_p : Heat capacity at constant _____.
 - C_v : Heat capacity at constant _____.
 - C_p usually > C_v

• Heat capacity has units of $\frac{J}{mol \cdot K}$ $\left(\frac{Btu}{lb - mol \cdot ^\circ F} \right)$

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Dependence of Heat Capacity on Temperature

- Heat capacity...
 - _____
 - for solids it reaches a limiting value of $3R$

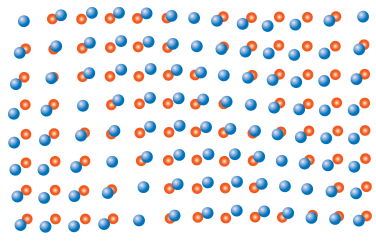


- From atomic perspective:
 - Energy is stored as _____.
 - As temperature increases, the average energy of atomic vibrations increases.

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Atomic Vibrations

Atomic vibrations are in the form of _____



● Normal lattice positions for atoms
● Positions displaced because of vibrations

Adapted from Fig. 19.1, Callister & Rethwisch 8e. Chapter 19 - 4

Specific Heat: Comparison

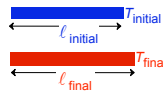
increasing c_p

Material	c_p (J/kg-K) at room T	
Polymers		
Polypropylene	1925	c_p (specific heat): (J/kg-K) C_p (heat capacity): (J/mol-K)
Polyethylene	1850	
Polystyrene	1170	
Teflon	1050	
Ceramics		
Magnesia (MgO)	940	<div style="border: 1px solid black; padding: 2px; display: inline-block;"> Why is c_p significantly larger for polymers? </div>
Alumina (Al ₂ O ₃)	775	
Glass	840	
Metals		
Aluminum	900	
Steel	486	
Tungsten	138	
Gold	128	

Selected values from Table 19.1, Callister & Rethwisch 8e. Chapter 19 - 5

Thermal Expansion

Materials change _____ when temperature is changed



$T_{final} > T_{initial}$

$$\frac{l_{final} - l_{initial}}{l_{initial}} = \alpha_l (T_{final} - T_{initial})$$

of
thermal expansion (1/K or 1/°C)

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Atomic Perspective: Thermal Expansion

Asymmetric curve:
 -- increase temperature,
 -- increase in interatomic separation
 -- thermal expansion

Symmetric curve:
 -- increase temperature,
 -- no increase in interatomic separation
 -- no expansion

Adapted from Fig. 19.3, Callister & Rethwisch 8e. Chapter 19 - 7

Coefficient of Thermal Expansion: Comparison

Material	α_L ($10^{-6}/^{\circ}\text{C}$) at room T
Polymers	
Polypropylene	145-180
Polyethylene	106-198
Polystyrene	90-150
Teflon	126-216
Metals	
Aluminum	23.6
Steel	12
Tungsten	4.5
Gold	14.2
Ceramics	
Magnesia (MgO)	13.5
Alumina (Al_2O_3)	7.6
Soda-lime glass	9
Silica (cryst. SiO_2)	0.4

Polymers have larger α_L values because of weak secondary bonds

Q: Why does α_L generally decrease with increasing bond energy?

Selected values from Table 19.1, Callister & Rethwisch 8e. Chapter 19 - 8

Thermal Expansion: Example

Ex: A copper wire 15 m long is cooled from _____ . How much change in length will it experience?

- Answer: For Cu $\alpha_L = 16.5 \times 10^{-6} (^{\circ}\text{C})^{-1}$
 rearranging Equation 19.3b
 $\Delta l = \alpha_L \ell_o \Delta T = [16.5 \times 10^{-6} (1/^{\circ}\text{C})](15 \text{ m})(40^{\circ}\text{C} - (-9^{\circ}\text{C}))$

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Thermal Conductivity

The ability of a material to _____.

Fourier's Law

$$q = -k \frac{dT}{dx}$$

q (J/m²-s) k thermal conductivity (J/m-K-s) $\frac{dT}{dx}$ temperature gradient

T_1 at x_1 T_2 at x_2 $T_2 > T_1$

- Atomic perspective: Atomic vibrations and free electrons in hotter regions transport energy to cooler regions.

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Thermal Conductivity: Comparison

Material	k (W/m-K)	Energy Transfer Mechanism
Metals		
Aluminum	247	atomic vibrations and motion of free electrons
Steel	52	
Tungsten	178	
Gold	315	
Ceramics		
Magnesia (MgO)	38	atomic vibrations
Alumina (Al ₂ O ₃)	39	
Soda-lime glass	1.7	
Silica (cryst. SiO ₂)	1.4	
Polymers		
Polypropylene	0.12	vibration/rotation of chain molecules
Polyethylene	0.46-0.50	
Polystyrene	0.13	
Teflon	0.25	

Selected values from Table 19.1, Callister & Rethwisch 8e. Chapter 19 - 11

Thermal Stresses

- Occur due to:
 - thermal expansion/contraction
 - temperature gradients that lead to differential dimensional changes

$$\text{stress} = \sigma = E\alpha_t(T_0 - T_f) = E\alpha_t\Delta T$$

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Example Problem

-- A brass rod is stress-free at _____.

-- It is heated up, but _____ from lengthening.

-- At what temperature does the stress reach -172 MPa?

Solution:

Original conditions: T_0 , l_0

Step 1: Assume _____ thermal expansion

$$\frac{\Delta l}{l_{room}} = \epsilon_{thermal} = \alpha_i (T_f - T_0)$$

Step 2: _____ specimen back to original length

$$\epsilon_{compress} = \frac{-\Delta l}{l_{room}} = -\epsilon_{thermal}$$

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Example Problem (cont.)

The _____ stress can be directly calculated as

$$\sigma = E(\epsilon_{compress})$$

Noting that $\epsilon_{compress} = -\epsilon_{thermal}$ and _____ gives

$$\sigma = -E(\epsilon_{thermal}) = -E\alpha_i(T_f - T_0) = E\alpha_i(T_0 - T_f)$$

Rearranging and solving for T_f gives

$T_f = T_0 - \frac{\sigma}{E\alpha_i}$ -172 MPa (since in compression)

Answer: _____ 100 GPa $20 \times 10^{-6} \text{ } ^\circ\text{C}$

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Thermal Shock Resistance

- Occurs due to: _____
- Ex: Assume top thin layer is rapidly cooled from T_1 to T_2

Temperature difference that can be produced by quenching:

$$(T_1 - T_2) = \frac{\text{quench rate}}{k}$$

Critical temperature difference for fracture (set $\sigma = \sigma_f$):

$$(T_1 - T_2)_{fracture} = \frac{\sigma_f}{E\alpha_i}$$

set _____


(quench rate)_{for fracture} = Thermal Shock Resistance (TSR) $\propto \frac{\sigma_f k}{E\alpha_i}$

- Large TSR when _____ is large

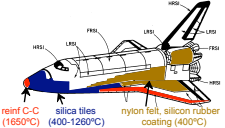
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Thermal Protection System

- Application:
 - Space Shuttle Orbiter



Chapter-opening photograph, Chapter 23, Callister 5e (courtesy of the National Aeronautics and Space Administration.)



reinf C-C (1650°C) silica tiles (400-1260°C) nylon felt, silicon rubber coating (400°C)

Fig. 19.2W, Callister 5e. (Fig. 19.2W adapted from L.J. Korb, C.A. Morant, R.M. Galland and C.S. Thacher, "The Shuttle Orbiter Thermal Protection System", Ceramic Bulletin, No. 11, Nov. 1981, p. 1189.)

- Silica tiles (400-1260°C):
 - large scale application


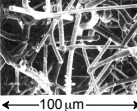


Fig. 19.3W, Callister 5e. (Fig. 19.3W courtesy the National Aeronautics and Space Administration.)



~90% porosity!
Si fibers bonded to one another during heat treatment.
100 μm

Fig. 19.4W, Callister 5e. (Fig. 219.4W courtesy Lockheed Aerospace Ceramics Systems, Sunnyvale, CA.)

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Summary

The thermal properties of materials include:

- **Heat capacity:**
 - energy required to increase a mole of material by a unit T
 - energy is stored as atomic vibrations
- **Coefficient of thermal expansion:**
 - the size of a material changes with a change in temperature
 - polymers have the largest values
- **Thermal conductivity:**
 - the ability of a material to transport heat
 - metals have the largest values
- **Thermal shock resistance:**
 - the ability of a material to be rapidly cooled and not fracture
 - is proportional to $\frac{\sigma_r k}{E \alpha_t}$

Chapter 19 - 17
